

FDW9926A

Dual N-Channel 2.5V Specified PowerTrench MOSFET

General Description

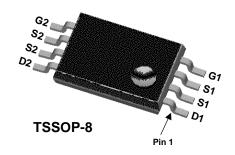
This N-Channel 2.5V specified MOSFET is a rugged gate version of Fairchild's Semiconductor's advanced PowerTrench process. It has been optimized for power management applications with a wide range of gate drive voltage (2.5V - 10V).

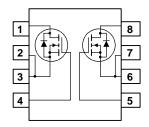
Applications

- Battery protection
- · Load switch
- · Power management

Features

- 4.5 A, 20 V. $R_{DS(ON)} = 32 \ m\Omega \ @ \ V_{GS} = 4.5 \ V$ $R_{DS(ON)} = 45 \ m\Omega \ @ \ V_{GS} = 2.5 \ V$
- Optimized for use in battery circuit applications
- Extended V_{GSS} range (±10V) for battery applications
- High performance trench technology for extremely low $R_{\mbox{\scriptsize DS}(\mbox{\scriptsize ON})}$
- Low profile TSSOP-8 package





Absolute Maximum Ratings TA=25°C unless otherwise noted

Symbol	Parameter		Ratings	Units
V _{DSS}	Drain-Source Voltage		20	V
V_{GSS}	Gate-Source Voltage		±12	V
I _D	Drain Current - Continuous	(Note 1a)	4.5	А
	– Pulsed		30	
P _D	Total Power Dissipation	(Note 1a)	1.0	W
		(Note 1b)	0.6	
T _J , T _{STG}	Operating and Storage Junction Temperature Range		-55 to +150	°C

Thermal Characteristics

$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient	(Note 1a)	125	°C/W
		(Note 1b)	208	

Package Marking and Ordering Information

Device Marking	Device	Reel Size	Tape width	Quantity
9926A	FDW9926A	13"	12mm	2500 units

Symbol	Parameter	Test Conditions	Min	Тур	Max	Units
Off Chara	acteristics			u l	ul	u.
BV _{DSS}	Drain-Source Breakdown Voltage	$V_{GS} = 0 \text{ V}, \qquad I_{D} = 250 \mu\text{A}$	20			V
$\frac{\Delta BV_{DSS}}{\Delta T_{J}}$	Breakdown Voltage Temperature Coefficient	$I_D = 250 \mu A$, Referenced to $25^{\circ}C$		12		mV/°C
I _{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 16 \text{ V}, \qquad V_{GS} = 0 \text{ V}$			1	μΑ
I _{GSS}	Gate-Body Leakage	$V_{GS} = \pm 12 \text{ V}, V_{DS} = 0 \text{ V}$			±100	nA
On Chara	acteristics (Note 2)					
V _{GS(th)}	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250 \mu A$	0.6	1.0	1.5	V
$\frac{\Delta V_{GS(th)}}{\Delta T_{,J}}$	Gate Threshold Voltage Temperature Coefficient	I_D = 250 μ A, Referenced to 25°C		-3		mV/°C
R _{DS(on)}	Static Drain-Source	$V_{GS} = 4.5 \text{ V}, I_D = 4.5 \text{ A}$		24	32	mΩ
	On–Resistance	$V_{GS} = 2.5 \text{ V}, I_{D} = 3.8 \text{ A}$		34	45	
		$V_{GS} = 4.5 \text{ V}, I_D = 4.5 \text{A}, T_J = 125^{\circ}\text{C}$		33	48	
I _{D(on)}	On–State Drain Current	$V_{GS} = 4.5 \text{ V}, V_{DS} = 5 \text{ V}$	15			Α
g _{FS}	Forward Transconductance	$V_{DS} = 5 \text{ V}, \qquad I_{D} = 4.5 \text{ A}$		19		S
Dynamic	Characteristics					
C _{iss}	Input Capacitance	$V_{DS} = 10 \text{ V}, \qquad V_{GS} = 0 \text{ V},$ $f = 1.0 \text{ MHz}$		630		pF
Coss	Output Capacitance			150		pF
C _{rss}	Reverse Transfer Capacitance			85		pF
R_{G}	Gate Resistance	$V_{GS} = 15 \text{ mV}, f = 1.0 \text{ MHz}$		1.4		Ω
Switchin	g Characteristics (Note 2)					
t _{d(on)}	Turn-On Delay Time	$V_{DD} = 10 \text{ V}, \qquad I_D = 1 \text{ A},$		8	16	ns
t _r	Turn-On Rise Time	$V_{GS} = 4.5 \text{ V}, \qquad R_{GEN} = 6 \Omega$		8	16	ns
t _{d(off)}	Turn-Off Delay Time			15	26	ns
t _f	Turn-Off Fall Time			4	8	ns
Q _g	Total Gate Charge	$V_{DS} = 10 \text{ V}, \qquad I_{D} = 4.5 \text{ A},$		6.1	9	nC
Q_{gs}	Gate-Source Charge	V _{GS} = 4.5 V		1.1		nC
Q_{gd}	Gate-Drain Charge			1.8		nC
Drain-Sc	ource Diode Characteristics a	and Maximum Ratings				
Is	Maximum Continuous Drain-Source				0.83	Α
V _{SD}	Drain–Source Diode Forward Voltage	$V_{GS} = 0 \text{ V}, I_S = 0.83 \text{ A} \text{(Note 2)}$		0.69	1.2	V
t _{rr}	Diode Reverse Recovery Time	I _F = 4.5 A,		14		nS
Q _{rr}	Diode Reverse Recovery Charge	$d_{iF}/d_t = 100 \text{ A/}\mu\text{s}$		4		nC

^{1.} R_{0JA} is the sum of the junction-to-case and case-to-ambient thermal resistance where the case thermal reference is defined as the solder mounting surface of the drain pins. $R_{\theta JC}$ is guaranteed by design while $R_{\theta CA}$ is determined by the user's board design.

a) $R_{\theta JA}$ is 125°C/W (steady state) when mounted on a 1 inch² copper pad on FR-4. b) $R_{\theta JA}$ is 208 °C/W (steady state) when mounted on a minimum copper pad on FR-4.

^{2.} Pulse Test: Pulse Width < 300μs, Duty Cycle < 2.0%

Typical Characteristics

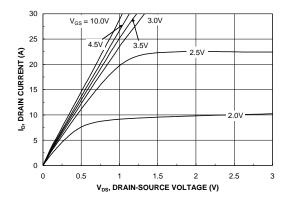


Figure 1. On-Region Characteristics.

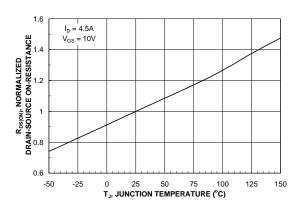


Figure 3. On-Resistance Variation with temperature.

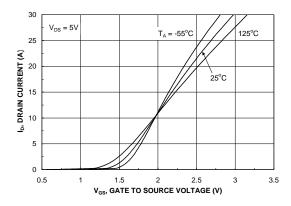


Figure 5. Transfer Characteristics.

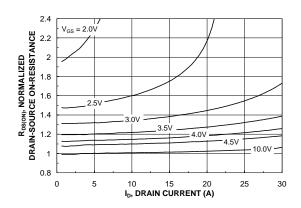


Figure 2. On-Resistance Variation with Drain Current and Gate voltage.

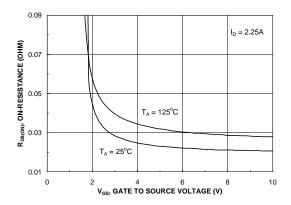


Figure 4. On-Resistance Variation with Gate-to-Source Voltage.

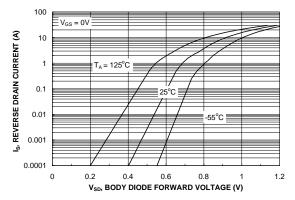
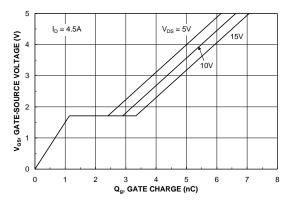


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature.

Typical Characteristics



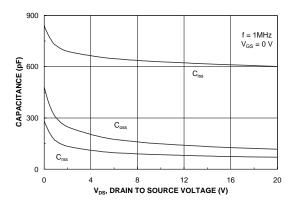
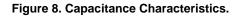
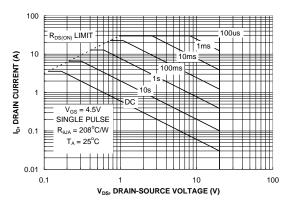


Figure 7. Gate Charge Characteristics.





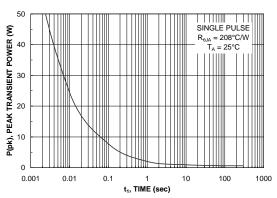


Figure 9. Maximum Safe Operating Area.

Figure 10. Single Pulse Maximum Power Dissipation.

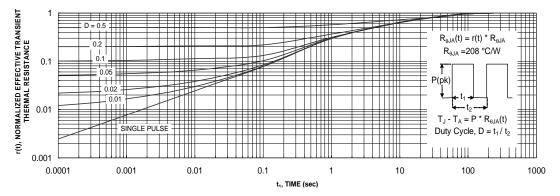


Figure 11. Transient Thermal Response Curve.

Thermal characterization performed using the conditions described in Note 1b. Transient thermal response will change depending on the circuit board design.





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